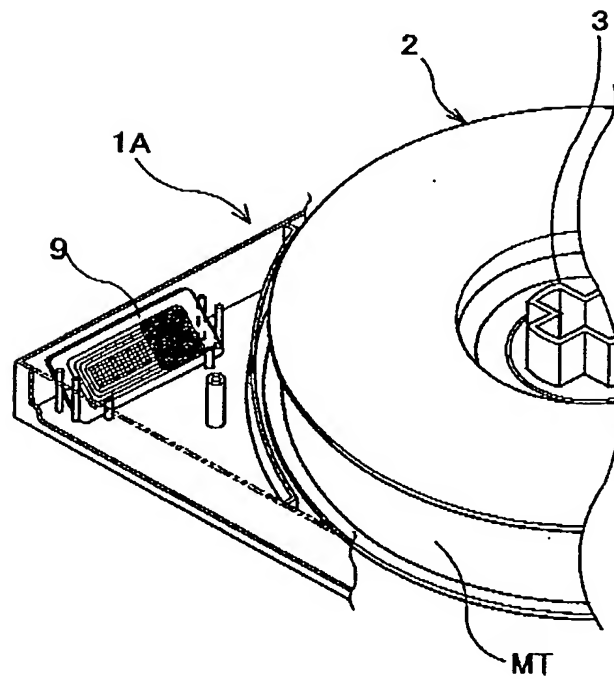


This diagram shows an exploded perspective view of a semiconductor device assembly. The assembly includes a top plate (1C) with a central opening, a spring (4), a central component (3) with a cross-shaped base (5), a triangular support (2) with a central hole, a circular base (1A) with a central opening, a side arm (MT) with a pin (10), a bottom frame (1C) with a central opening, and a side component (6) with a pin (7). The assembly is shown in a disassembled state, with arrows indicating the relative positions and movement of the components. The label 'MC' is at the top right, and 'MT' is on the right side. The label '1' is on the left side, with '1A' and '1B' indicating different parts of the assembly. The label '8' is at the bottom left, and '9' is at the bottom center. The label '1C' appears twice, once on the top plate and once on the bottom frame.

FIG.2

(a)



(b)

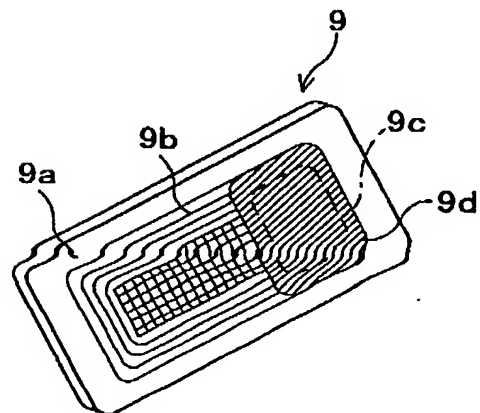


FIG. 3

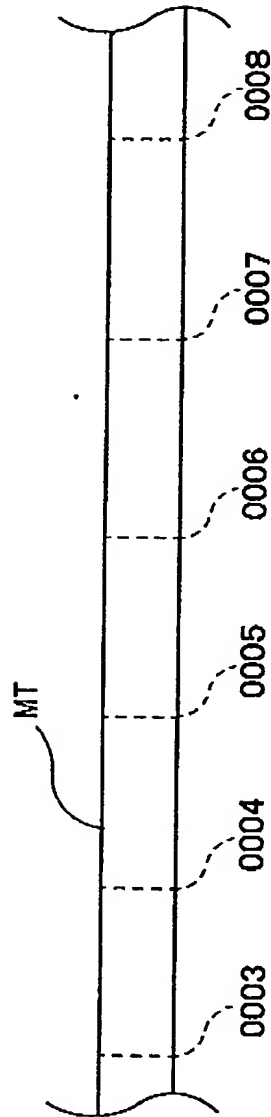


FIG.4

(a)

ADDRESS	INFORMATION
↑	↑
0003	0
0004	1
0005	0
0006	1
0007	0
0008	0
↑	↑

(b)

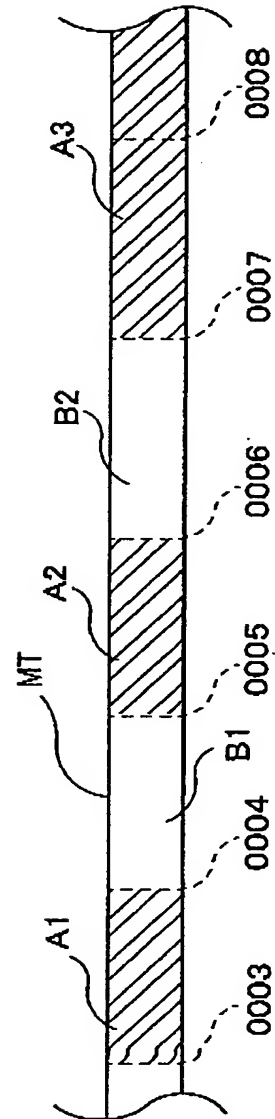


FIG.5

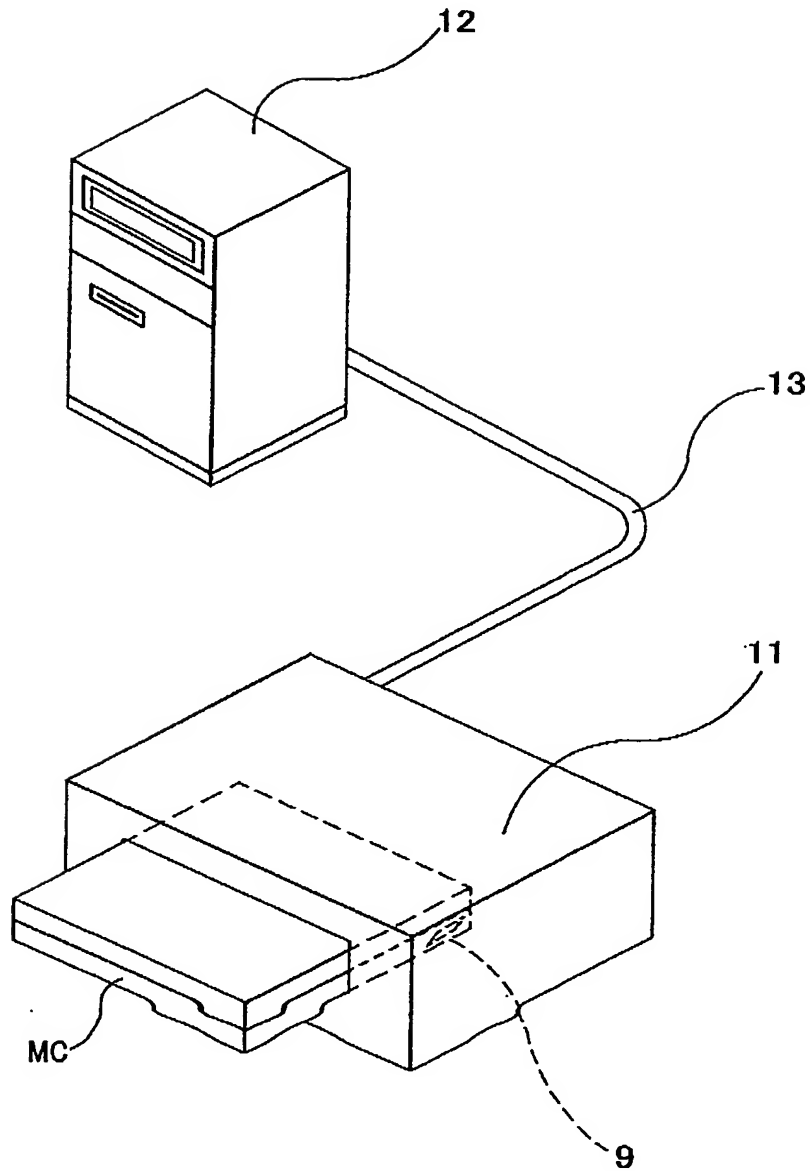


FIG.6

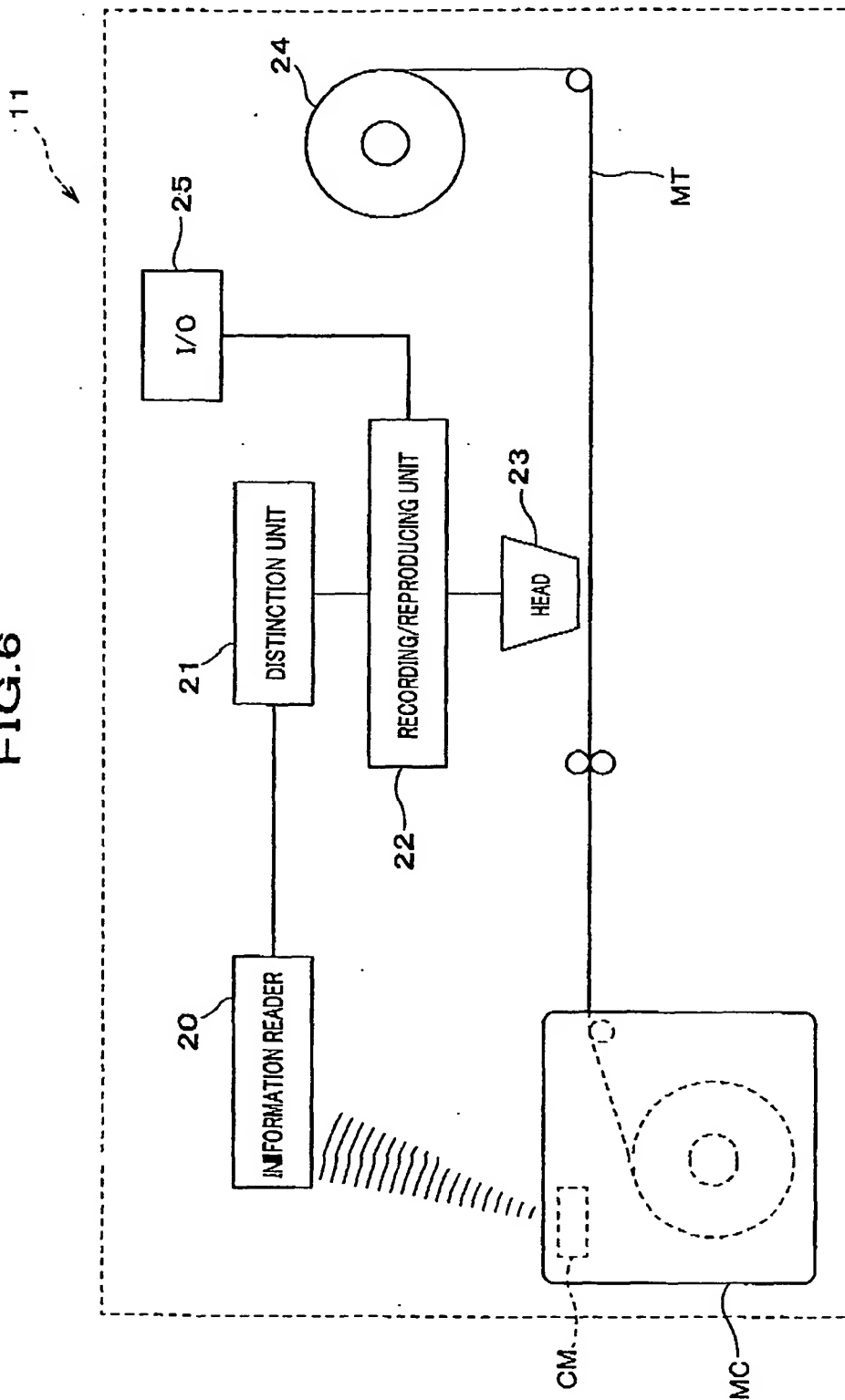


FIG. 7

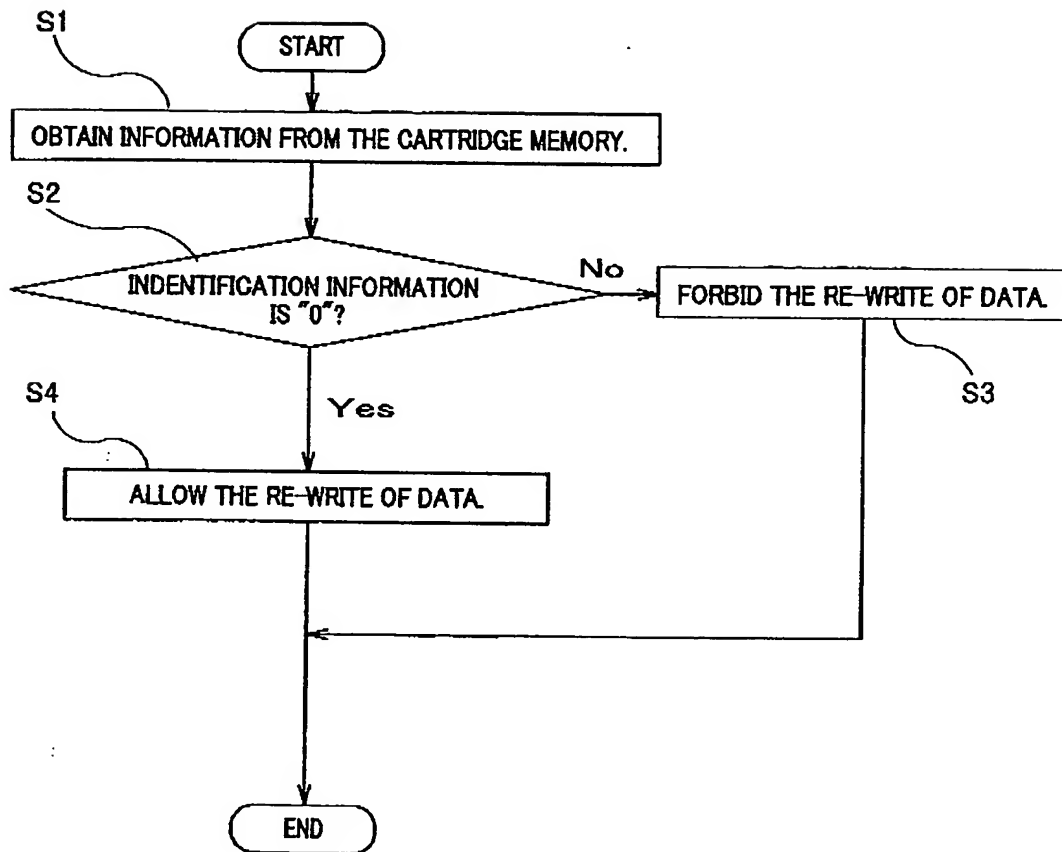


FIG. 8

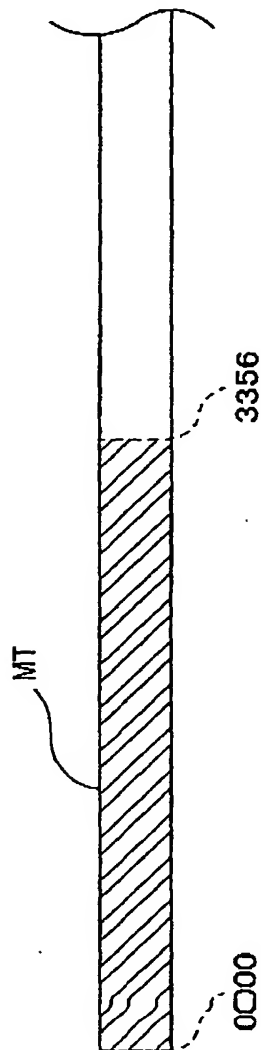




FIG. 9

(a)

ADDRESS	INFORMATION
...	...
0003	1
0005	0
0007	1
0018	0
...	...

(b)

